Recommended PCB Pad Layouts for 8 Land USON & WSON Packages

1.0 Introduction

This application note specifies the recommended Printed Circuit Board pad layouts for the following 8-USON and 8-WSON packages.

2x3mm USON 8L
4x4mm USON 8L
6x5mm WSON 8L
8x6mm WSON 8L

2.0 2x3mm USON 8L

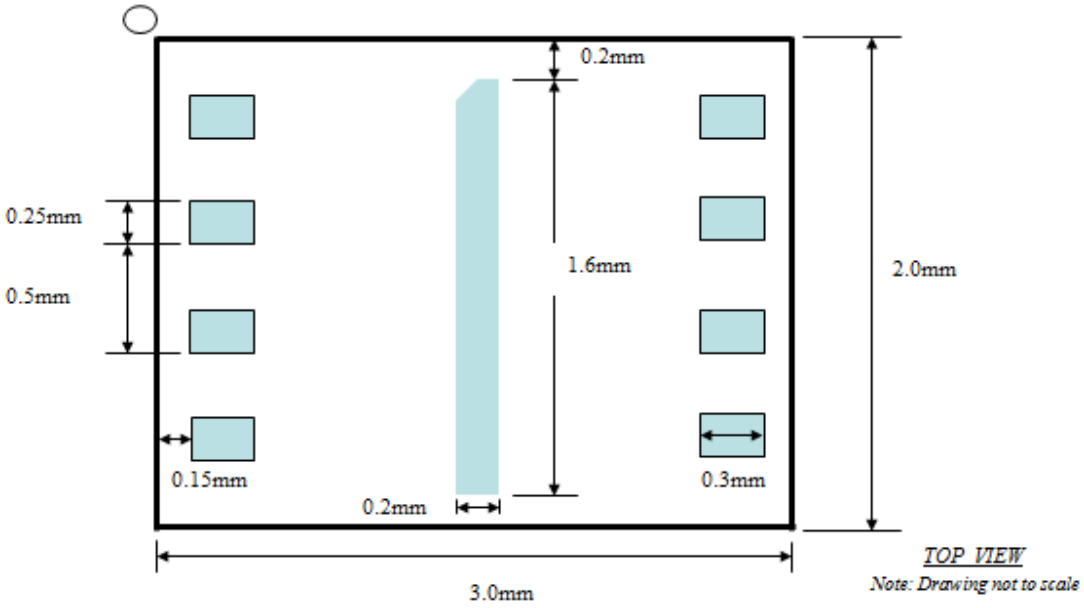

Figure-1: PCB Pad Layout for 2x3mm 8-USON

Notes:

1. Solid lines indicate the package outline.

2. Blue shaded areas indicate metal pad locations. The use of a solder mask between metal pads on the PCB is recommended.

3. The exposed metal center pad is not needed for heat dissipation.
Please leave a keep-out area underneath the exposed metal center pad and avoid placing vias or traces in the keep-out area.
This is to prevent the exposed metal pad from accidentally shorting to a via or trace.
Another option is to put a pad underneath the exposed center metal pad, but leave the pad floating.
On some devices, the exposed metal center pad can be connected to the same ground as the GND pin of the package, but please check device datasheet package information to confirm that this option is allowable.

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3.0 4x4mm USON 8L

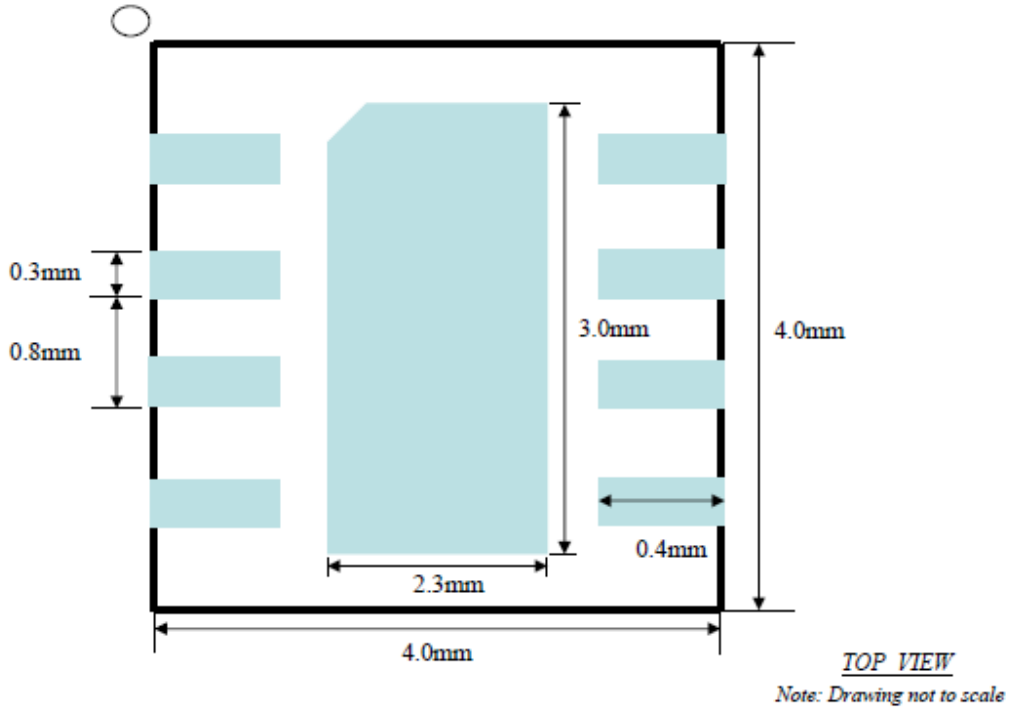

Figure-2: PCB pad layout 4x4mm 8-USON

Notes:
1. Solid lines indicate the package outline.
2. Blue shaded areas indicate metal pad locations. The use of a solder mask between metal pads on the PCB is recommended.
3. The exposed metal center pad is not needed for heat dissipation.
Please leave a keep-out area underneath the exposed metal center pad and avoid placing vias or traces in the keep-out area.
This is to prevent the exposed metal pad from accidentally shorting to a via or trace.
Another option is to put a pad underneath the exposed center metal pad, but leave the pad floating.
On some devices, the exposed metal center pad can be connected to the same ground as the GND pin of the package,
but please check device datasheet package information to confirm that this option is allowable.

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4.0 6x5mm WSON 8L

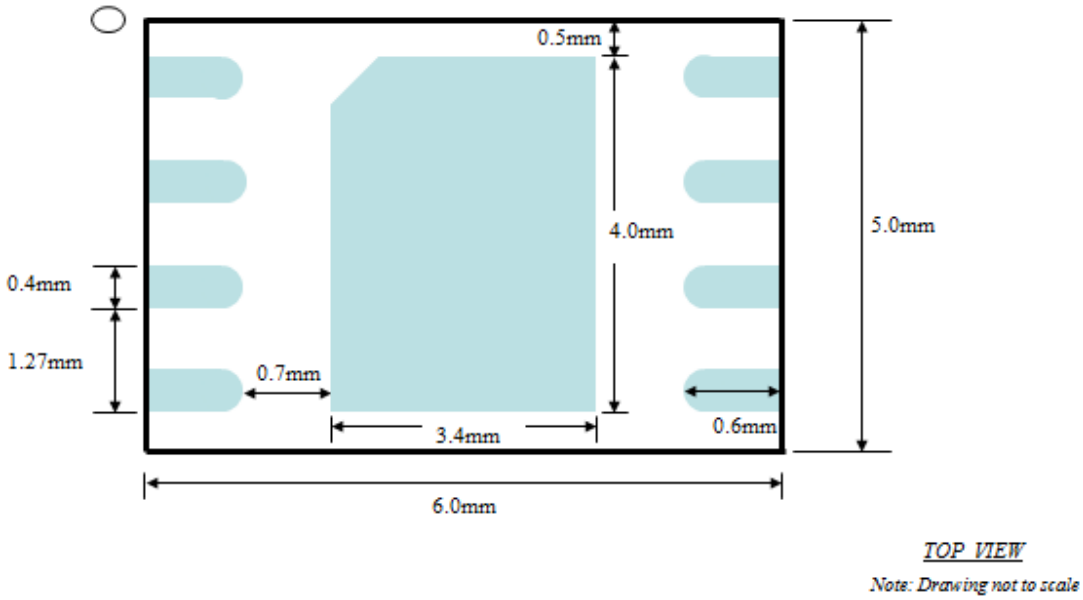

Figure-3: PCB pad layout for 6x5mm 8-WSON

Notes:
1. Solid lines indicate the package outline.
2. Blue shaded areas indicate metal pad locations. The use of a solder mask between metal pads on the PCB is recommended.
3. The exposed metal center pad is not needed for heat dissipation.
Please leave a keep-out area underneath the exposed metal center pad and avoid placing vias or traces in the keep-out area.
This is to prevent the exposed metal pad from accidentally shorting to a via or trace.
Another option is to put a pad underneath the exposed center metal pad, but leave the pad floating.
On some devices, the exposed metal center pad can be connected to the same ground as the GND pin of the package,
but please check device datasheet package information to confirm that this option is allowable.

5.0 8x6mm WSON 8L

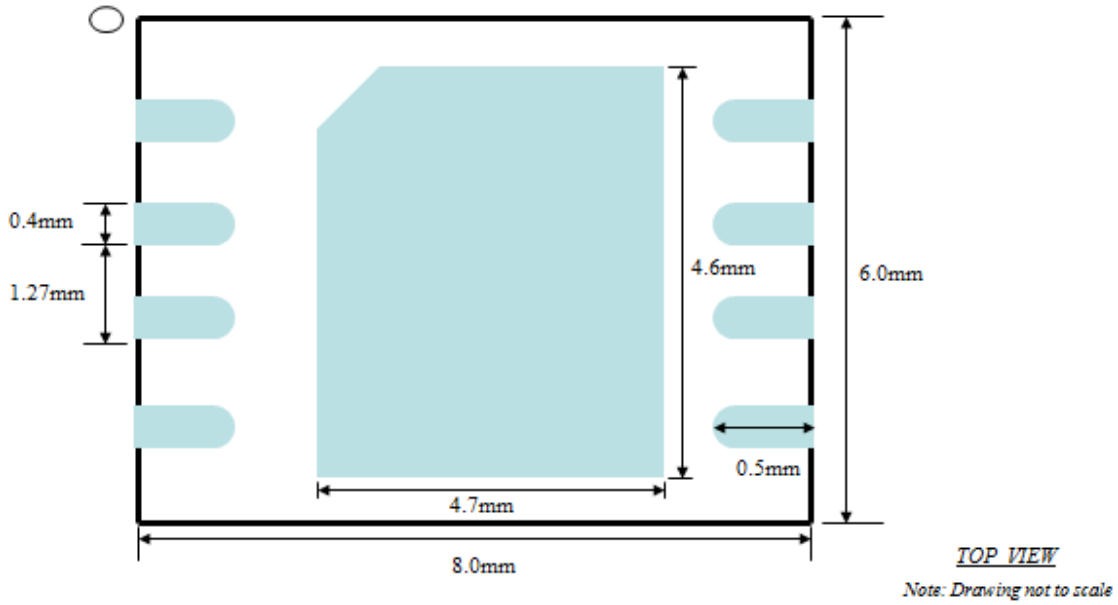

Figure-4: PCB pad layout for 8x6mm 8-WSON

Notes:
1. Solid lines indicate the package outline.
2. Blue shaded areas indicate metal pad locations. The use of a solder mask between metal pads on the PCB is recommended.
3. The exposed metal center pad is not needed for heat dissipation.
Please leave a keep-out area underneath the exposed metal center pad and avoid placing vias or traces in the keep-out area.
This is to prevent the exposed metal pad from accidentally shorting to a via or trace.
Another option is to put a pad underneath the exposed center metal pad, but leave the pad floating.
On some devices, the exposed metal center pad can be connected to the same ground as the GND pin of the package, but please check device datasheet package information to confirm that this option is allowable.

6. Revision History

Revision	Description	Date
2.0	Initial Release	May 15, 2012
3.0	Modify PCB Pad Size to match component typical dimensions instead of min/max dimensions.	Mar. 31, 2016

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